

Thus, the objections to the specification are respectfully believed to have been overcome.

In the claims

Please amend the claims as follows. All pending claims are rewritten below in clean form pursuant to Rule 1.121 (c) (1) (i).

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- B1
1. (Twice Amended) An electronic device comprising:  
a leadframe having a die carrier and a plurality of leads having a first surface formed having bump indentations and a second surface formed having bump terminals; and  
a semiconductor die having a surface supported by the die carrier, wherein the surface is formed with a plurality of conductive bumps for directly attaching to the plurality of bump indentations.
  2. The electronic device of Claim 1, wherein the top of the leads are coplanar with a die carrier.
  3. The electronic device of Claim 1, wherein the device is encapsulated using a one sided process.
  6. The electronic device of Claim 1, further comprising a mold lock region.
  7. The electronic device of Claim 1, further comprising two rows of leads.